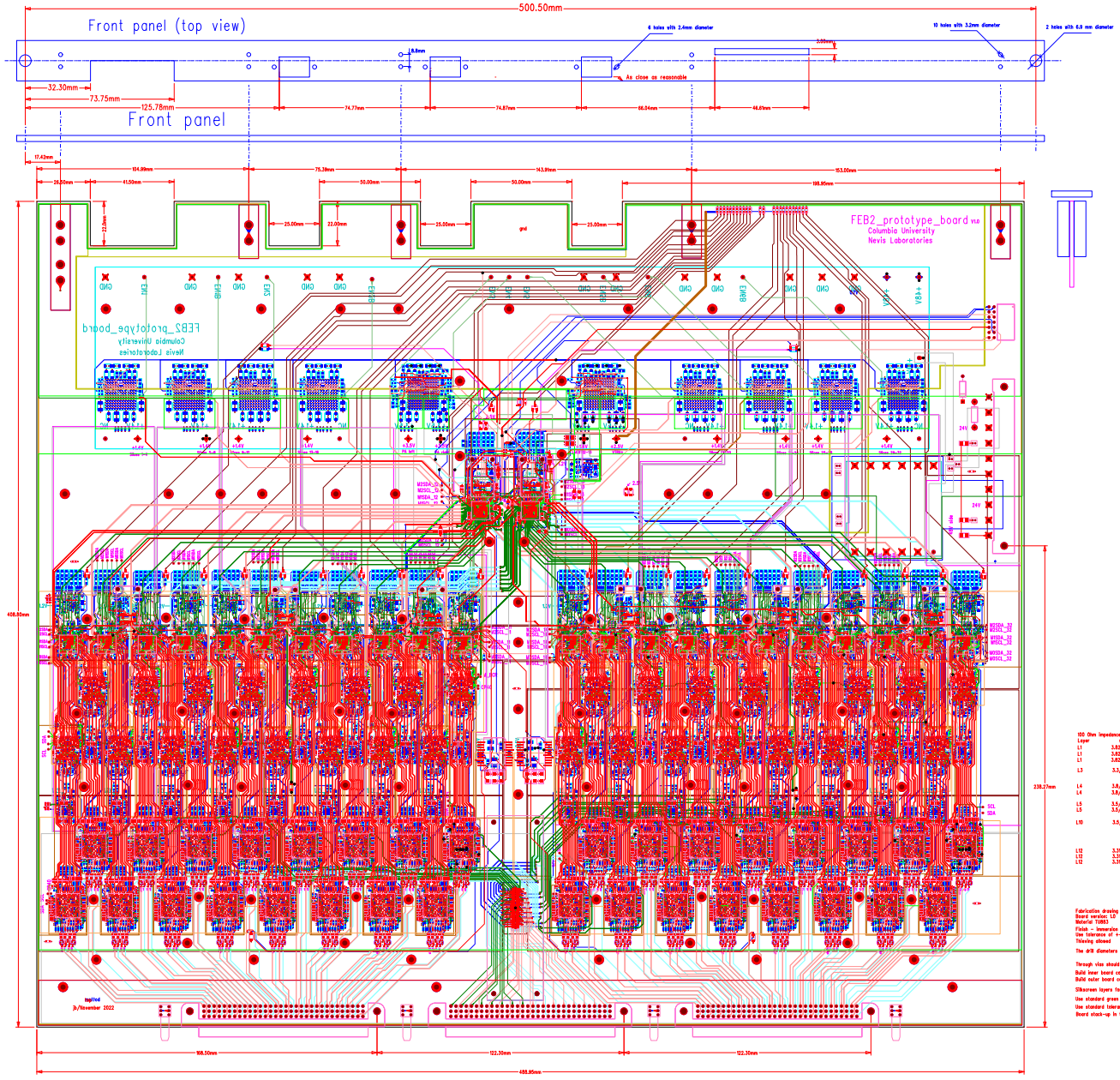

100 Ohm impedance diff line structures (to be tuned)

Layer	w/s	reference layer
L1	3.82/5	L3
L1	3.82/5.31	L2
L1	3.82/5.39	L2
L3	3.3/4.2	L2/L4
L4	3.8/4.02	L3/L5
L4	3.8/3.94	L3/L5
L5	3.5/4.02	L4/L6
L5	3.5/3.88	L4/L6
L10	3.5/4.00	L9/L11
L12	3.31/4.17	L11/L13
L12	3.31/4.21	L11/L13
L12	3.31/4.25	L11/L13

Fabrication drawing for FEB2_prototype_board .
Board version: 1.0
Material TU883
Finish – Immersion gold
Use tolerance of +-5.00" for hole-to-edge dimensions.
Thieving allowed

The drill diameters for component holes are finished hole diameters

Through vias should be solder filled.
Build inner board corners with 1.0mm radius
Build outer board corners with 1.0mm radius

Silkscreen layers for top and bottom layers.

Use standard green solder mask.
Use standard tolerances for hole sizes.
Board stack-up in the file FEB2_stack_up.xlsx .